

Crystal LTD TM SPEC Form

Customer

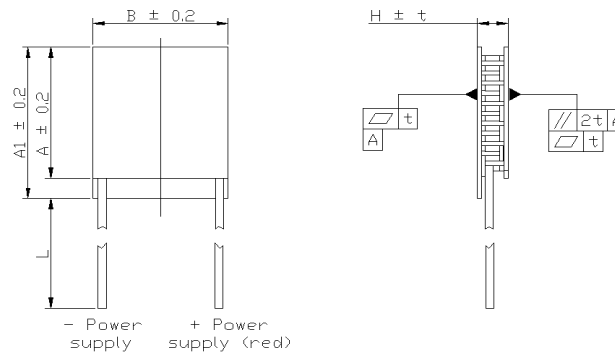
PO#

PO date

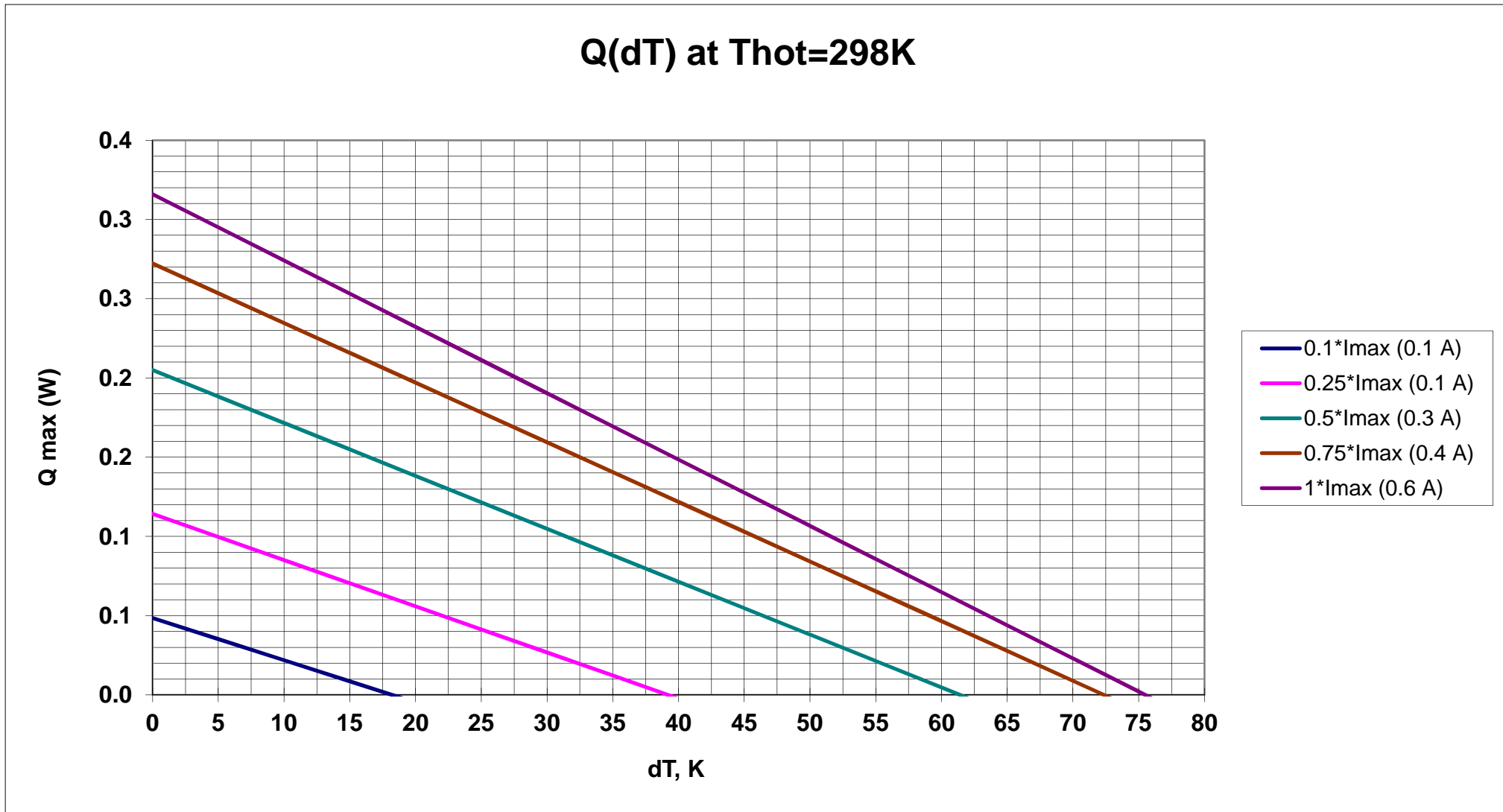
Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Parameters in vacuum at hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	continuous operation	I _{max} , A	U _{max} , V	Q _{max} , W	dT _{max} , K	Rac, Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, AWG #	Length, mm	Tolerance ±, mm	
1	S-007-05-20	138	130	115	0.6	0.9	0.3	75.5	1.18	10	4/4	4	3.40	0.2	30	100	5	
															solid tinned uninsulated			

Clamping force: 0.2 - 0.4 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



U(dT) at Thot=298K

